

Product Summary

BV_{DSS}	$R_{DS(on)}$	I_D $T_A = +25^\circ C$
100V	350mΩ @ $V_{GS} = 10V$	2.4A
	450mΩ @ $V_{GS} = 6.0V$	2.1A

Description and Applications

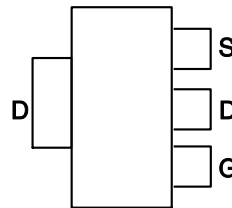
This MOSFET is designed to minimize the on-state resistance and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Motor Control
- DC-DC Converters
- Power Management Functions
- Uninterrupted Power Supply

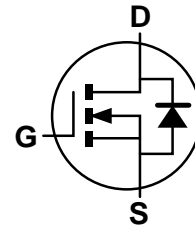
SOT223



Top View



Pin Out - Top View



Equivalent Circuit

Features and Benefits

- Fast Switching Speed
- Low Gate Drive
- Low Input Capacitance
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

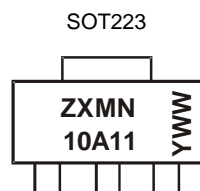
- Case: SOT223
- Case Material: Molded Plastic; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208
- Weight: 0.112 grams (Approximate)

Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXMN10A11GTA	See Below	7	12	1,000

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



ZXMN10A11 = Product Type Marking Code
 YWW = Date Code Marking
 Y or \bar{Y} = Last Digit of Year (ex: 5= 2015)
 WW or $\bar{W}W$ = Week Code (01-53)

Maximum Ratings (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

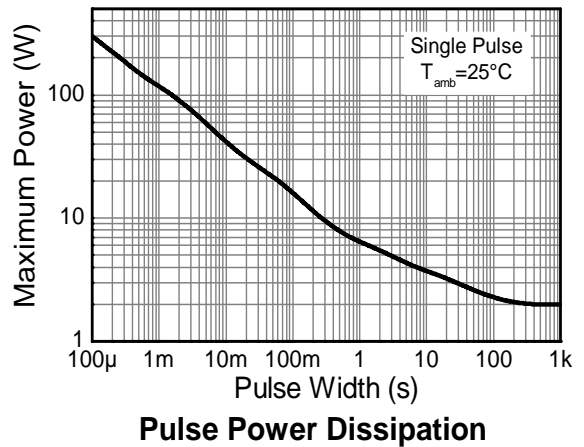
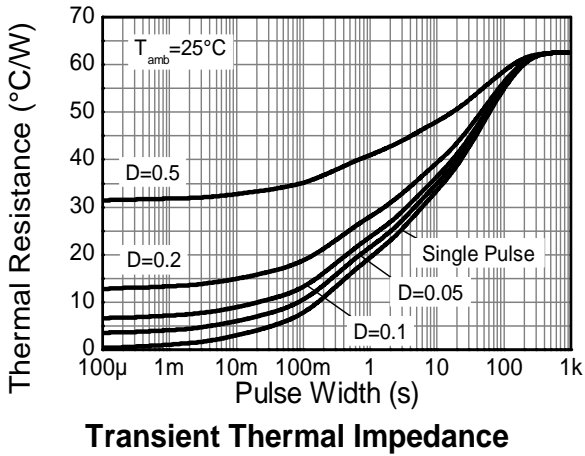
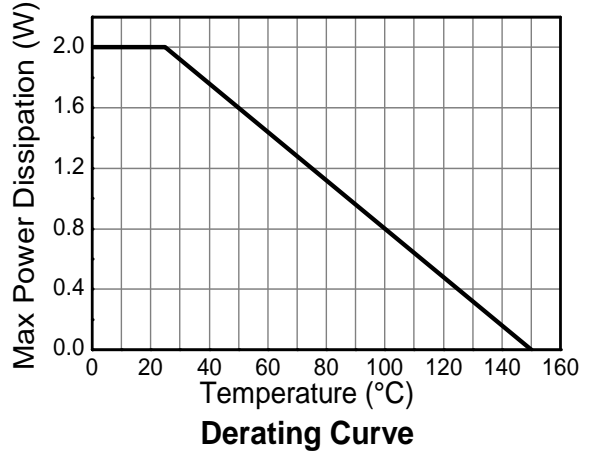
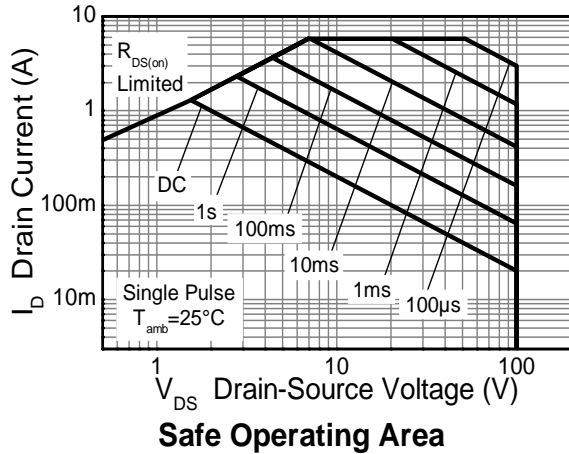
Characteristic			Symbol	Value	Unit	
Drain-Source Voltage			V_{DSS}	100	V	
Gate-Source Voltage			V_{GS}	± 20	V	
Continuous Drain Current	$V_{GS} = 10\text{V}$	(Note 6)	I_D	2.4	A	
		$T_A = +70^\circ\text{C}$ (Note 6)		1.9		
		(Note 5)		1.7		
Pulsed Drain Current	$V_{GS} = 10\text{V}$	(Note 7)	I_{DM}	7.9	A	
Continuous Source Current (Body Diode)			(Note 6)	I_S	4.6	A
Pulsed Source Current (Body Diode)			(Note 7)	I_{SM}	7.9	A

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$ unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Power Dissipation	Linear Derating Factor	(Note 5)	P_D	2.0	W
		(Note 6)		16	
Thermal Resistance, Junction to Ambient		(Note 5)	$R_{\theta JA}$	3.9	$\text{mW}/^\circ\text{C}$
		(Note 6)		31	
Thermal Resistance, Junction to Lead		(Note 5)	$R_{\theta JL}$	62.5	$^\circ\text{C}/\text{W}$
		(Note 6)		32.0	
Operating and Storage Temperature Range			T_J, T_{STG}	9.8	$^\circ\text{C}/\text{W}$
				-55 to 150	$^\circ\text{C}$

- Notes:
5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
 6. Same as Note 5, except the device is measured at $t \leq 10$ seconds.
 7. Same as Note 5, except the device is pulsed with $D = 0.02$ and pulse width 300 μs . The pulse current is limited by the maximum junction temperature.
 8. Thermal resistance from junction to solder-point (at the end of the drain lead).

Thermal Characteristics

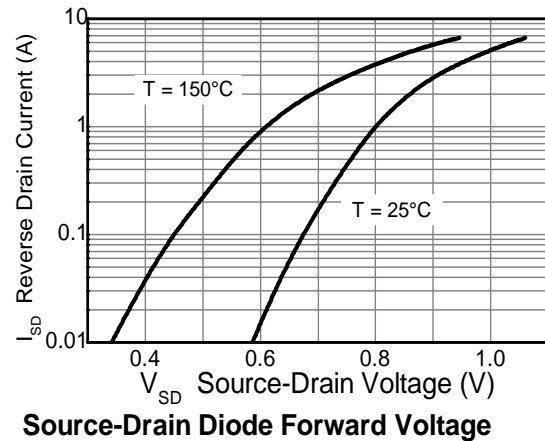
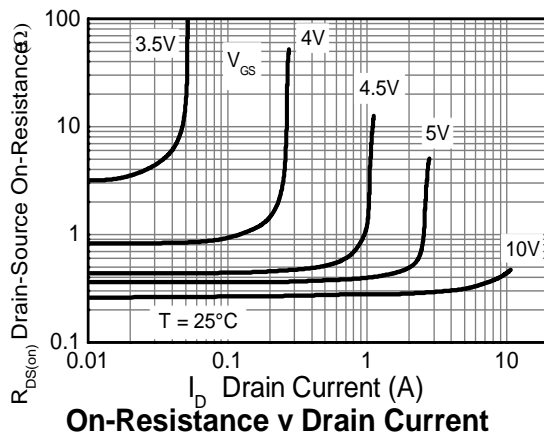
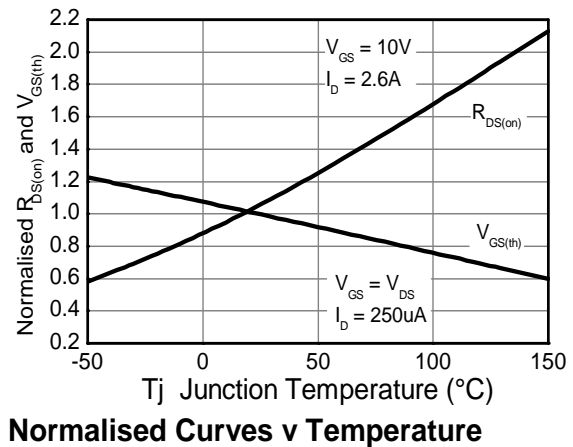
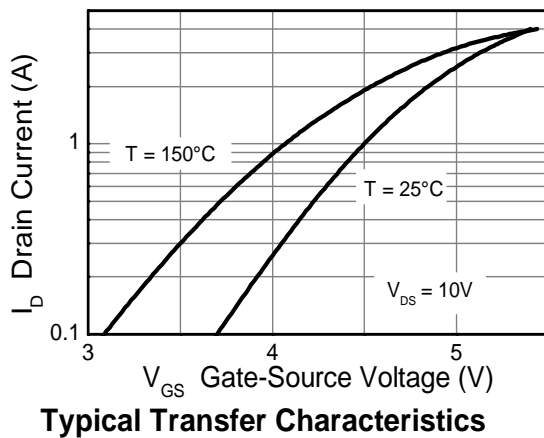
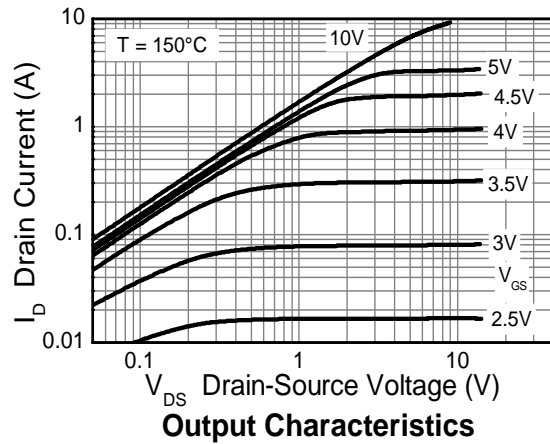
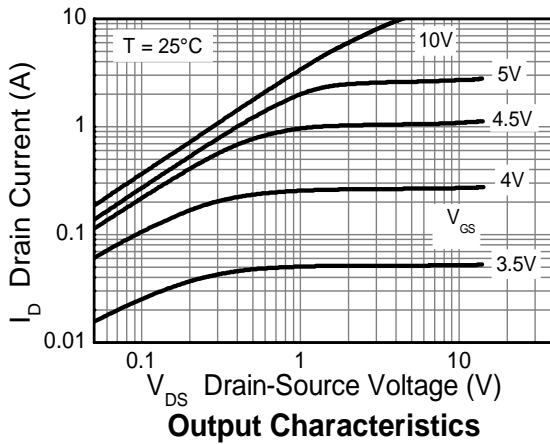


Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

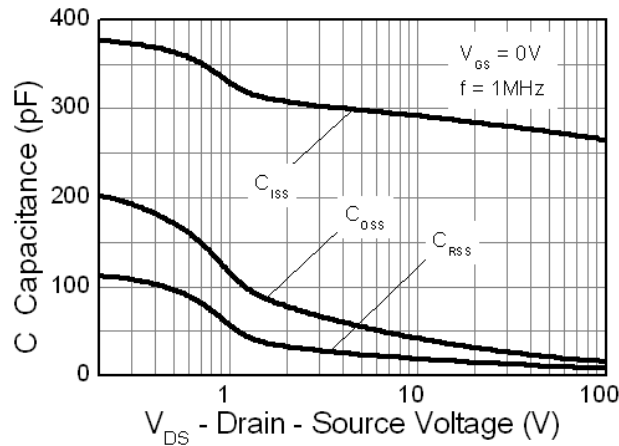
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage	BV _{DSS}	100	—	—	V	I _D = 250μA, V _{GS} = 0V	
Zero Gate Voltage Drain Current	I _{DSS}	—	—	1	μA	V _{DS} = 100V, V _{GS} = 0V	
Gate-Source Leakage	I _{GSS}	—	—	±100	nA	V _{GS} = ±20V, V _{DS} = 0V	
ON CHARACTERISTICS							
Gate Threshold Voltage	V _{GS(th)}	2.0	—	4.0	V	I _D = 250μA, V _{DS} = V _{GS}	
Static Drain-Source On-Resistance (Note 9)	R _{DS(on)}	—	—	0.35	Ω	V _{GS} = 10V, I _D = 2.6A	
				0.45		V _{GS} = 6V, I _D = 1.3A	
Forward Transconductance (Notes 9 & 10)	g _{fs}	—	4	—	S	V _{DS} = 15V, I _D = 2.6A	
Diode Forward Voltage (Note 9)	V _{SD}	—	0.85	0.95	V	I _S = 1.85A, V _{GS} = 0V	
Reverse Recovery Time (Note 10)	t _{rr}	—	26	—	ns	I _F = 1.0A, di/dt = 100A/μs	
Reverse Recovery Charge (Note 10)	Q _{rr}	—	30	—	nC		
DYNAMIC CHARACTERISTICS (Note 6)							
Input Capacitance	C _{iss}	—	274	—	pF	V _{DS} = 50V, V _{GS} = 0V f = 1MHz	
Output Capacitance	C _{oss}	—	21	—	pF		
Reverse Transfer Capacitance	C _{rss}	—	11	—	pF		
Total Gate Charge (Note 11)	Q _g	—	3.5	—	nC	V _{GS} = 6.0V	V _{DS} = 50V I _D = 2.5A
Total Gate Charge (Note 11)	Q _g	—	5.4	—	nC	V _{GS} = 10V	
Gate-Source Charge (Note 11)	Q _{gs}	—	1.4	—	nC		
Gate-Drain Charge (Note 11)	Q _{gd}	—	1.5	—	nC		
Turn-On Delay Time (Note 11)	t _{D(on)}	—	2.7	—	ns	V _{DD} = 50V, V _{GS} = 10V I _D = 1A, R _G ≅ 6.0Ω	
Turn-On Rise Time (Note 11)	t _r	—	1.7	—	ns		
Turn-Off Delay Time (Note 11)	t _{D(off)}	—	7.4	—	ns		
Turn-Off Fall Time (Note 11)	t _f	—	3.5	—	ns		

- Notes:
9. Measured under pulsed conditions. Pulse width ≤ 300μs; duty cycle ≤ 2%.
 10. For design aid only, not subject to production testing.
 11. Switching characteristics are independent of operating junction temperatures.

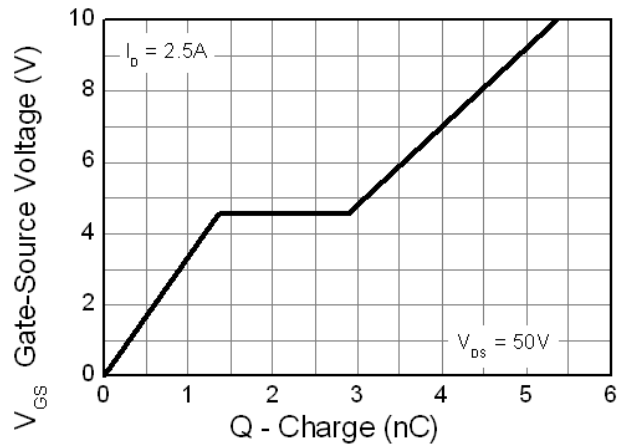
Typical Characteristics



Typical Characteristics (cont.)

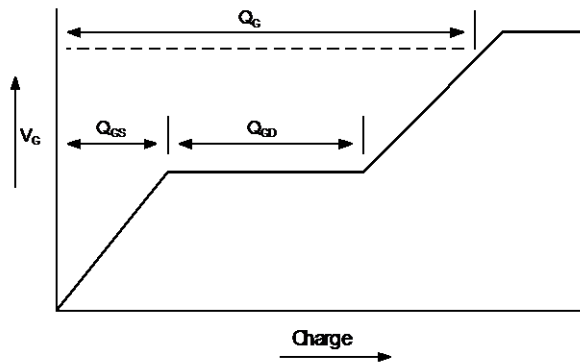


Capacitance v Drain-Source Voltage

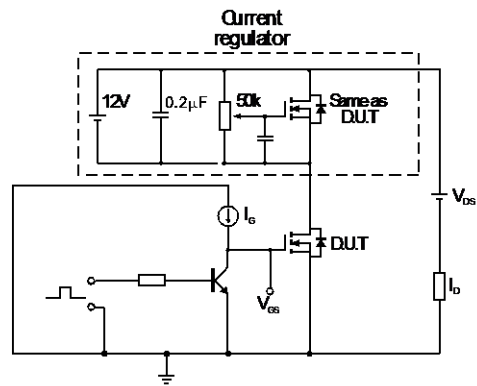


Gate-Source Voltage v Gate Charge

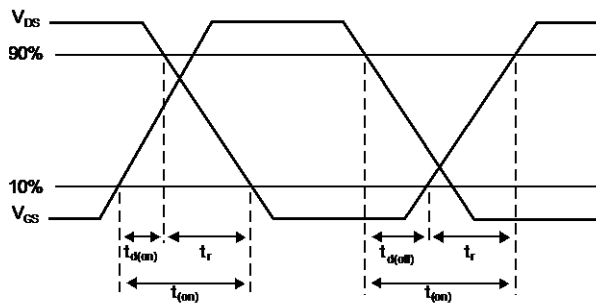
Test Circuits



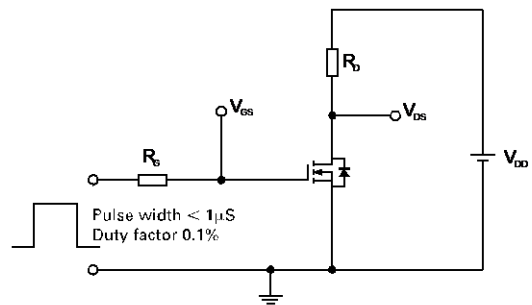
Basic gate charge waveform



Gate charge test circuit



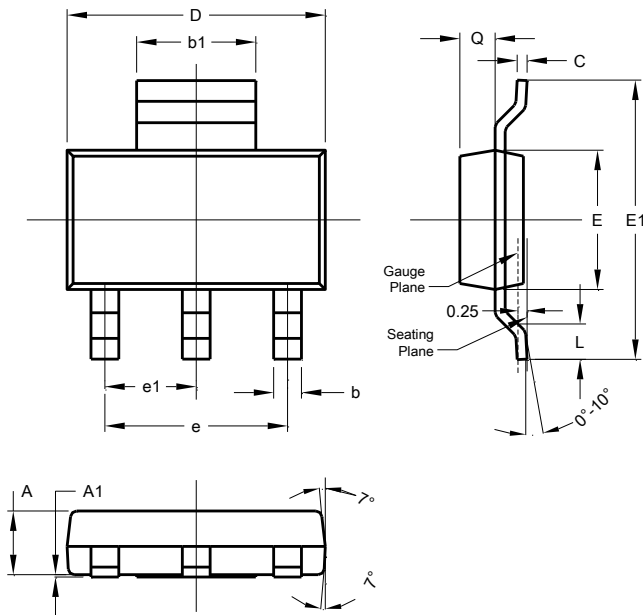
Switching time waveforms



Switching time test circuit

Package Outline Dimensions

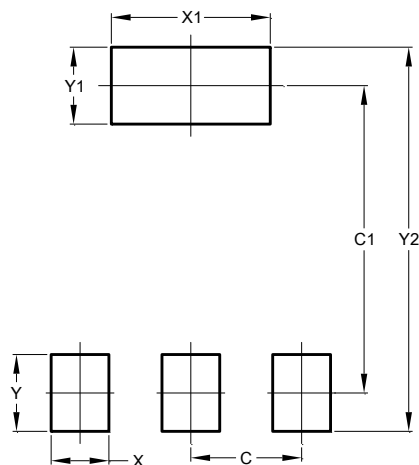
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for the latest version.



SOT223			
Dim	Min	Max	Typ
A	1.55	1.65	1.60
A1	0.010	0.15	0.05
b	0.60	0.80	0.70
b1	2.90	3.10	3.00
C	0.20	0.30	0.25
D	6.45	6.55	6.50
E	3.45	3.55	3.50
E1	6.90	7.10	7.00
e	-	-	4.60
e1	-	-	2.30
L	0.85	1.05	0.95
Q	0.84	0.94	0.89
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
C	2.30
C1	6.40
X	1.20
X1	3.30
Y	1.60
Y1	1.60
Y2	8.00

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